

SOT1173-1

plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; resin based

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN64R
Package type industry code	HVQFN64R
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	2-4-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.9	-	9	9.1	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	0.75	-	0.8	0.9	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	64	-	



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2. Package outline

HVQFN64R: plastic thermal enhanced very thin quad flat package; no leads; 64 terminals; resin based; body 9 x 9 x 0.8 mm

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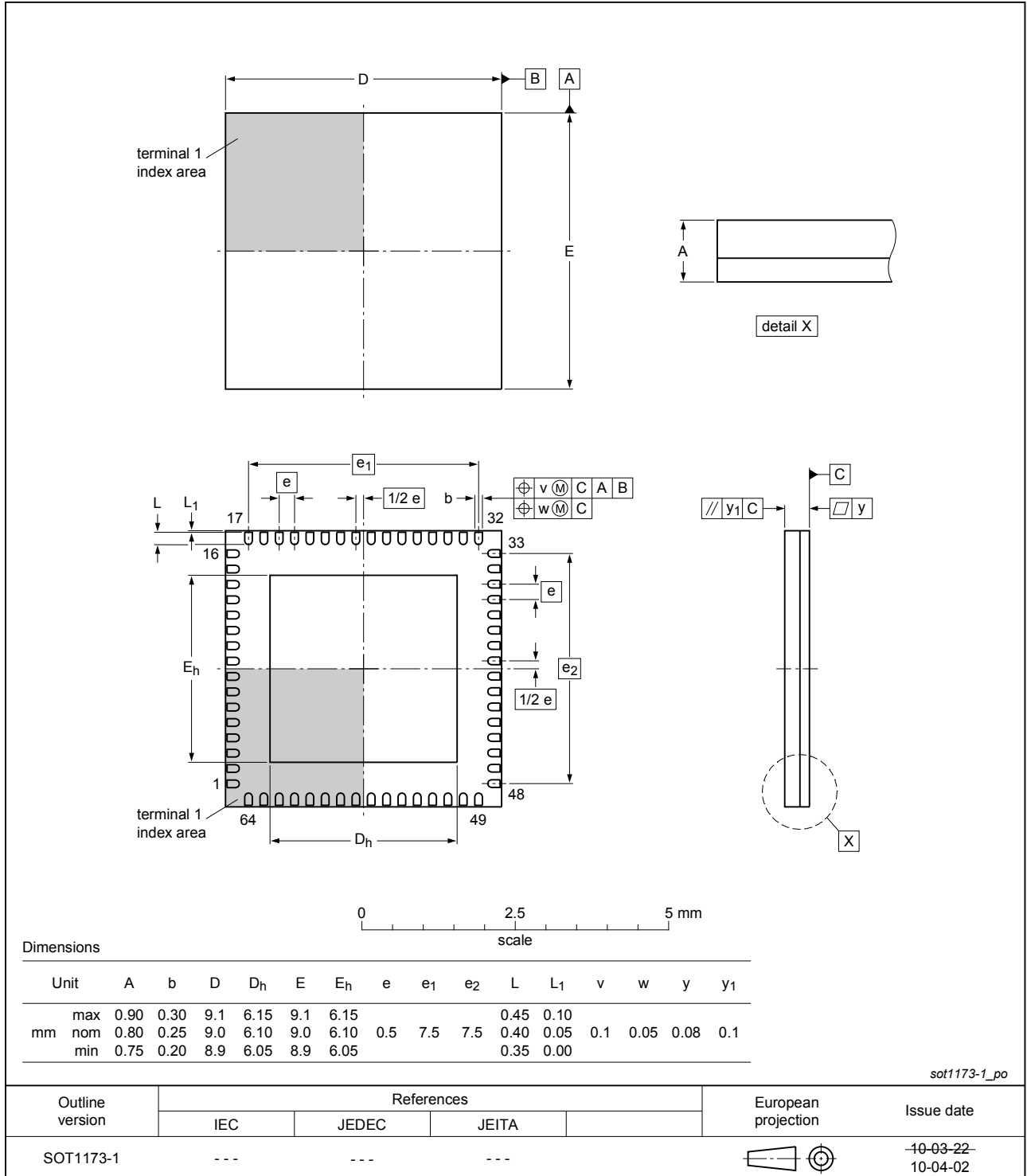


Fig. 1. Package outline HVQFN64R (SOT1173-1)

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3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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